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PATENT APPLICATION

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Makoto KOBAYASHI et al.

Group Art Unit: 3723

Application No.: 09/830,434

Examiner: H. Shakeri

Filed: April 26, 2001

Docket No.: 109352

For: POLISHING PAD AND POLISHING METHOD FOR SEMICONDUCTOR WAFER

AMENDMENT

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

RECEIVED  
MAY 05 2003  
TECHNOLOGY CENTER R3700

Sir:

In reply to the April 29, 2003 Office Action, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 11-13, 20 and 27-31 as follows:

11. (Twice Amended) A polishing pad used for polishing a semiconductor wafer while supplying a polishing agent onto the polishing pad in a mirror polishing process, wherein a content of zinc oxide (ZnO) included in the polishing pad is 200ppm or less at the ratio of zinc weight relative to the weight of the polishing pad.

12. (Twice Amended) A polishing pad used for polishing a semiconductor wafer while supplying a polishing agent onto the polishing pad in a finish polishing process, wherein a content of zinc oxide (ZnO) included in the polishing pad is 100ppm or less at the ratio of zinc weight relative to the weight of the polishing pad.